Title: Datasheet for bg25606						
Proposed 1 st Ship Date: Dec. 6, 2017						
Change Type:						
Assembly Site Design Wafer Bump Site						
Assembly Process Image: Construction of the second secon						
Assembly Materials Part number change Wafer Bump Process						
Mechanical Specification Test Site Wafer Fab Site						
Packing/Shipping/Labeling Test Process Wafer Fab Materials						
Wafer Fab Process						
Notification Details						
Description of Change:						
Texas Instruments Incorporated is announcing an information only notification.						
The product datasheet(s) is being updated as summarized below.						
Lia Texas bq25606						
INSTRUMENTS						
SLUSCK6A – MAY 2017 – REVISED AUGUST 2017						
Changes from Original (May 2017) to Revision A Page						
Updated data sheet title						
Deleted 200 nS Fast Turn-Off in Features						
Updated Simplified Application schematic						
Changed ACDRV pin references to "NC" in <i>Pin Configuration and Functions</i> section						
Deleted ACDRV pin references from <i>Pin Functions</i> table						
Updated VAC pin description in <i>Pin Functions</i> table						
Deleted ACDRV pin references from <i>Absolute Maximum Ratings</i> table						
Added ESD Ratings table						
Deleted VAC debounce time from <i>Timing Requirements</i> table						
Updated Functional Block Diagram						
Updated Power Up from Input Source section						
Deleted Power Up OVPFET section						
Deleted OVPFET Startup Control timing illustration						
Updated Input Overvoltage (ACOV) section						
Updated <i>bq25606 Application Diagram</i> schematic						
The datasheet number will be changing.						
Device Family Change From: Change To:						
bq25606 SLUSCK6 SLUSCK6A						
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/bq25606						
Reason for Change:						
Bq25606 will not ssupport external OVP (Over Voltage Protection) FET configuration.						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):						
The part was specified for 2 applications to support or not support external OVP FET. The						
customer impact is: External OVP FET is no longer supported by the device. There will be no						
impact to customer designs without external OVP FET.						
Changes to product identification resulting from this PCN:						

None.		
Product Affected:		
BQ25606RGER	BQ25606RGET	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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